



Customer Information Notification

201310005I

Issue Date: 17-Oct-2013
Effective Date: 01-Mar-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to [view this notification online](#)



Change Category

- | | | | |
|---|---|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input checked="" type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change to newer generation tool for 200mm wafer backside metallization

Information Notification

For the wafer backside metallization of our audio amplifier products produced on 200mm wafers a newer generation metal deposition tool will be used, leading to an adapted metal stack on the backside metal.

- TiNiAg layer will change to TiNiVAg layer
 - Ti thickness will be modified from 120nm +/-20nm to 100nm +/-15nm
- The change does not imply any change to product fit, form and function.

Product and process qualification will be finished in Q1/2014
After NXP release the change will be implemented as running change in the production and deliveries.
Material from the current flow will be used until material in progress and stocks are fully depleted.
The final product identification will not change - type name, 12NC and product marking stay the same.
The change will be traceable by the date code per product type.

Implementation is planned for Q1/2014

Why do we issue this Information Notification

- Reason for change is to secure future deliveries
- The tools currently used for 200mm wafer backside metallization are reaching their end of life
 - The production capacity of the current tool is restricted

Identification of Affected Products

Product identification does not change
The change will be traceable by the date code per product type.

Impact

no impact to the product's functionality anticipated.
The change does not imply any change to product fit, form and function.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Commercial Marketing Manager
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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